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**RESPONSE UNDER 37 C.F.R. § 1.116
EXPEDITED PROCEDURE - EXAMINING GROUP 1700**

PATENT

I hereby certify that on the date specified below, this correspondence is being deposited with the United States Postal Service as first-class mail in an envelope addressed to Mail Stop AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

November 17, 2006

Date

Denise Sheridan
Denise Sheridan

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : 09/974,958

Confirmation No. : 7582

Applicants : Vernon M. Williams et al.

Filed : October 10, 2001

Attorney Docket No.: 501062.01

Art Unit : 1722

Customer No. : 27,076

Examiner : Robert B. Davis

Title : LEADFRAME AND METHOD FOR REDUCING MOLD COMPOUND ADHESION PROBLEMS

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE UNDER 37 C.F.R. § 1.116

Sir:

Applicants acknowledge receipt of the Office Action dated September 7, 2006.

Please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Amendments to the Drawings begin on page 8 of this paper and include both annotated and replacement sheets.

Remarks begin on page 9 of this paper.

An Appendix including amended drawing figures is attached following page 12 of this paper.

DO NOT ENTER

11/29/06 TP